



DOCKET NO: 268844US0PCT

"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 1765"

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
HIROSHI SHIHO, ET AL. : EXAMINER: CHEN, KIN CHAN
SERIAL NO: 10/529,742 :
FILED: JANUARY 6, 2006 : GROUP ART UNIT: 1765
FOR: POLISHING PAD FOR :
SEMICONDUCTOR WAFER AND
LAMINATED BODY FOR POLISHING OF
SEMICONDUCTOR WAFER EQUIPPED
WITH THE SAME AS WELL AS
METHOD FOR POLISHING OF
SEMICONDUCTOR WAFER

REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the Office Action of June 8, 2007, Applicants request reconsideration
in view of the following remarks.

Remarks begin on page 2 of this paper.

Reconsideration only
8/15/07

KCC